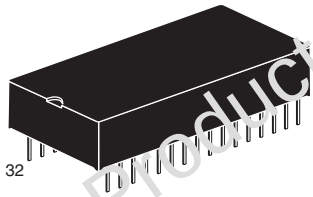
M48Z129V

3.3 V, 1 Mbit (128 Kb x 8) ZEROPOWER® SRAM

Not recommended for new design

Features

- Integrated, ultra low power SRAM, power-fail control circuit, and battery
- Conventional SRAM operation; unlimited WRITE cycles
- 10 years of data retention in the absence of power
- Microprocessor power-on reset (reset valid even during battery backup mode)
- Battery low pin - provides warning of battery end-of-life
- Automatic power-fail chip deselect and WRITE protection
- WRITE protect voltages
  - V_{CC} = 3.0 to 3.6 V; 2.7 V ≤ V_{PFD} ≤ 3.0 V (V_{PFD} = power-fail deselect voltage)
- Self-contained battery in the CAPHAT™ DIP package
- Pin and function compatible with JEDEC standard 128 K x 8 SRAMs
- RoHS compliant
  - Lead-free second level interconnect



PMDIP32 module

This is information on a product still in production but not recommended for new designs. www.st.com

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1 Description

The M48Z129V ZEROPOWER® SRAM is a 1,048,576 bit non-volatile static RAM organized as 131,072 words by 8 bits. The device combines an internal lithium battery, a CMOS SRAM and a control circuit in a plastic 32-pin DIP module. The M48Z129V directly replaces industry standard 128 K x 8 SRAM. It also provides the non-volatility of FLASH without any requirement for special WRITE timing or limitations on the number of WRITEs that can be performed.

Figure 1. Logic diagram

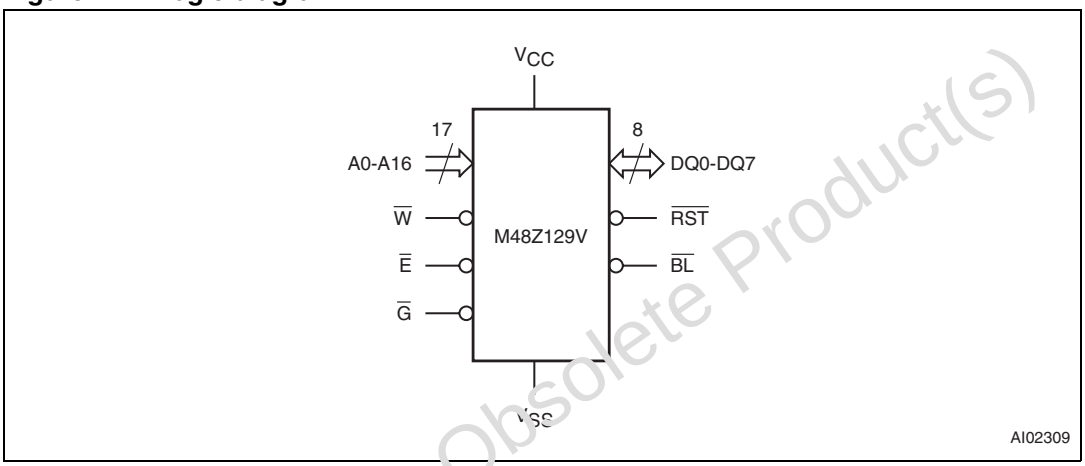


Table 1. Signal names

A0-A16	Address inputs
DQ0-DQ7	Data inputs / outputs
$\overline{E}$	Chip enable
$\overline{G}$	Output enable
$\overline{W}$	WRITE enable
$\overline{RST}$	Reset output (open drain)
$\overline{BL}$	Battery low output (open drain)
V_{CC}	Supply voltage
V_{SS}	Ground

Figure 2. DIP connections

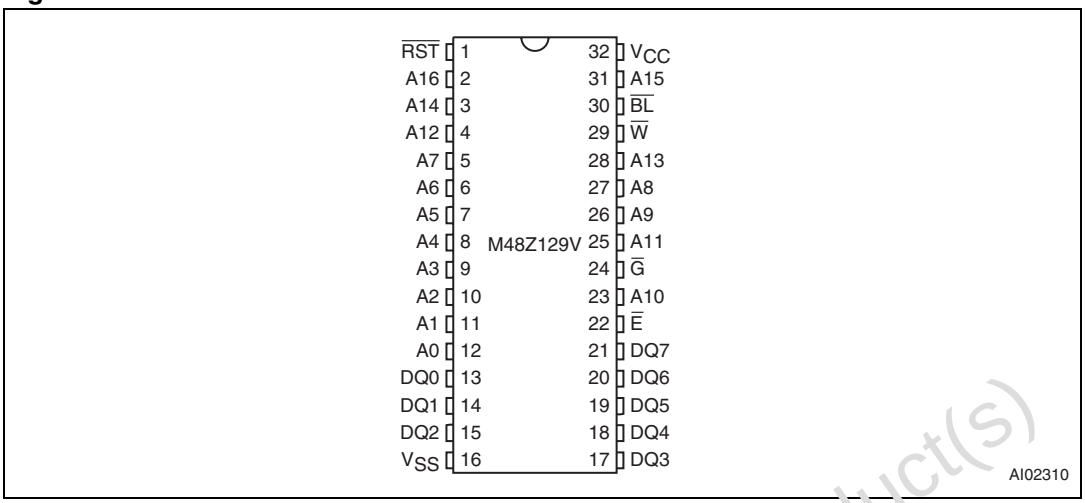
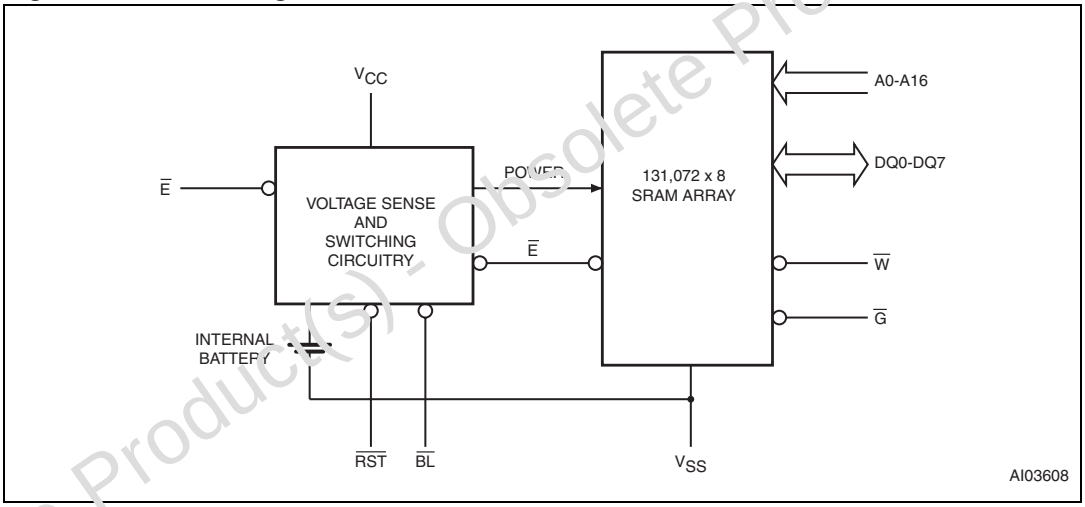


Figure 3. Block diagram



2 Operation modes

The M48Z129V also has its own power-fail detect circuit. This control circuitry constantly monitors the supply voltage for an out of tolerance condition. When V_{CC} is out of tolerance, the circuit write protects the SRAM, providing data security in the midst of unpredictable system operation. As V_{CC} falls, the control circuitry automatically switches to the battery, maintaining data until valid power is restored.

Table 2. Operating modes

Mode	V_{CC}	$\overline{E}$	$\overline{G}$	$\overline{W}$	DQ0-DQ7	Power
Deselect	4.5 to 5.5 V or 3.0 to 3.6 V	V_{IH}	X	X	High Z	Standby
WRITE		V_{IL}	X	V_{IL}	D_{IN}	Active
READ		V_{IL}	V_{IL}	V_{IH}	D_{OUT}	Active
READ		V_{IL}	V_{IH}	V_{IH}	High Z	Active
Deselect	V_{SO} to V_{PFD} (min)(1)	X	X	X	High Z	CMOS standby
Deselect	$\leq V_{SO}$(1)	X	X	X	High Z	Battery backup mode

1. See *Table 10* for details.

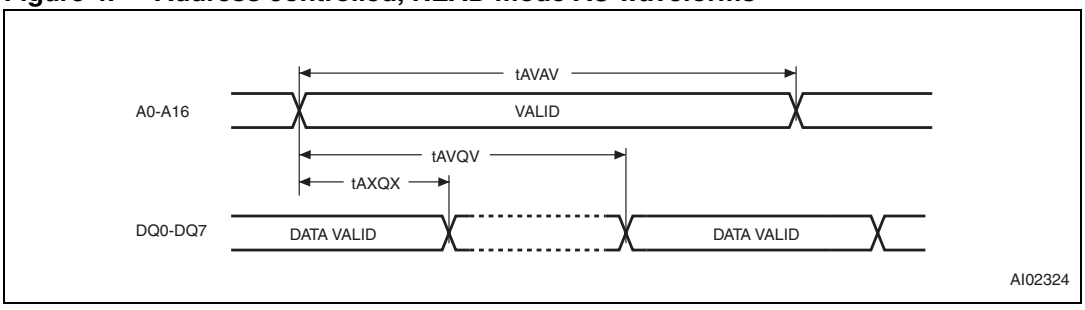
Note: X = V_{IH} or V_{IL}; V_{SO} = battery backup switchover voltage

2.1 READ mode

The M48Z129V is in the READ mode whenever $\overline{W}$ (WRITE enable) is high and $\overline{E}$ (chip enable) is low. The unique address specified by the 17 address inputs defines which one of the 131,072 bytes of data is to be accessed. Valid data will be available at the data I/O pins within t_{AVQV} (address access time) after the last address input signal is stable, providing the $\overline{E}$ and $\overline{G}$ access times are also satisfied. If the $\overline{E}$ and $\overline{G}$ access times are not met, valid data will be available after the latter of the chip enable access times (t_{ELQV}) or output enable access time (t_{GLQV}).

The state of the eight three-state data I/O signals is controlled by $\overline{E}$ and $\overline{G}$. If the outputs are activated before t_{AVQV}, the data lines will be driven to an indeterminate state until t_{AVQV}. If the address inputs are changed while $\overline{E}$ and $\overline{G}$ remain active, output data will remain valid for t_{AXQX} (output data hold time) but will go indeterminate until the next address access.

Figure 4. Address controlled, READ mode AC waveforms



Note: Chip enable ($\overline{E}$) and output enable ($\overline{G}$) = low, WRITE enable ($\overline{W}$) = high

Figure 5. Chip enable or output enable controlled, READ mode AC waveforms

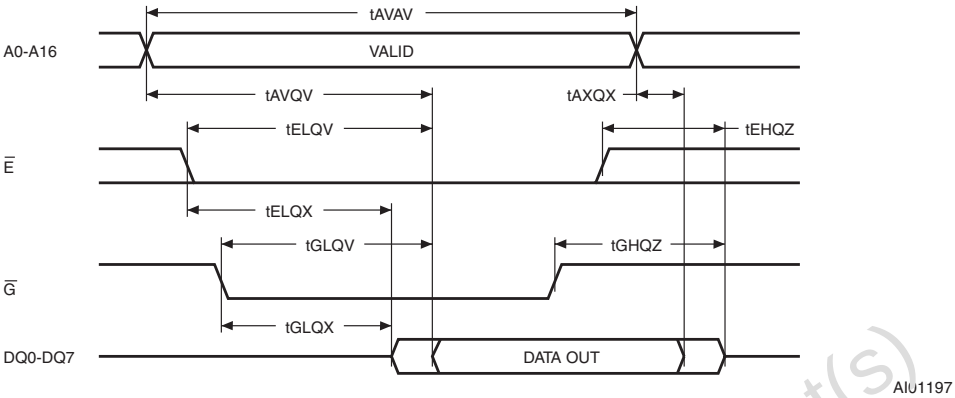


Table 3. READ mode AC characteristics

Symbol	Parameter[1]	Min	Max	Unit
t_{AVAV}	READ cycle time	85		ns
t_{AVQV}	Address valid to output valid		85	ns
t_{ELQV}	Chip enable low to output valid		85	ns
t_{GLQV}	Output enable low to output valid		45	ns
t_{ELQX}[2]	Chip enable low to output transition	5		ns
t_{GLQX}[2]	Output enable low to output transition	5		ns
t_{EHQZ}[2]	Chip enable high to output Hi-Z		40	ns
t_{GHQZ}[2]	Output enable high to output Hi-Z		25	ns
t_{AXQX}	Address transition to output transition	5		ns

1. Valid for ambient operating temperature: T_A = 0 to 70 °C; V_{CC} = 3.0 to 3.6 V (except where noted).
2. C_L = 5pF (see Figure 9).

2.2 WRITE mode

The M48Z129V is in the WRITE mode whenever $\overline{W}$ (WRITE enable) and $\overline{E}$ (chip enable) are active. The start of a WRITE is referenced from the latter occurring falling edge of $\overline{W}$ or $\overline{E}$. A WRITE is terminated by the earlier rising edge of $\overline{W}$ or $\overline{E}$. The addresses must be held valid throughout the cycle. $\overline{E}$ or $\overline{W}$ must return high for a minimum of t_{EHAX} from chip enable or t_{WHAX} from WRITE enable prior to the initiation of another READ or WRITE cycle. Data-in must be valid t_{DVWH} prior to the end of WRITE and remain valid for t_{WHDX} afterward. $\overline{G}$ should be kept high during WRITE cycles to avoid bus contention; although, if the output bus has been activated by a low on $\overline{E}$ and $\overline{G}$ a low on $\overline{W}$ will disable the outputs t_{WLQZ} after $\overline{W}$ falls.

Figure 6. WRITE enable controlled, WRITE mode AC waveform

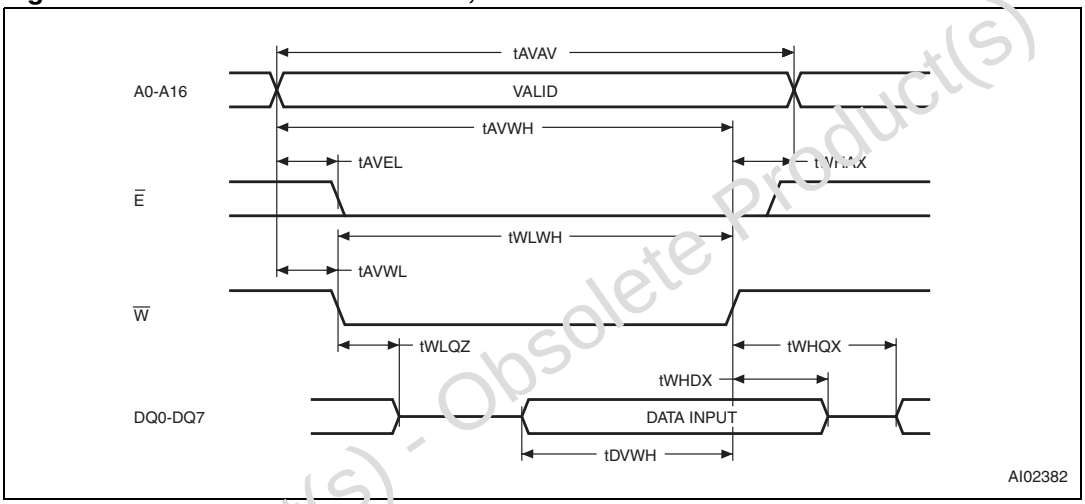


Figure 7. Chip enable controlled, WRITE mode AC waveforms

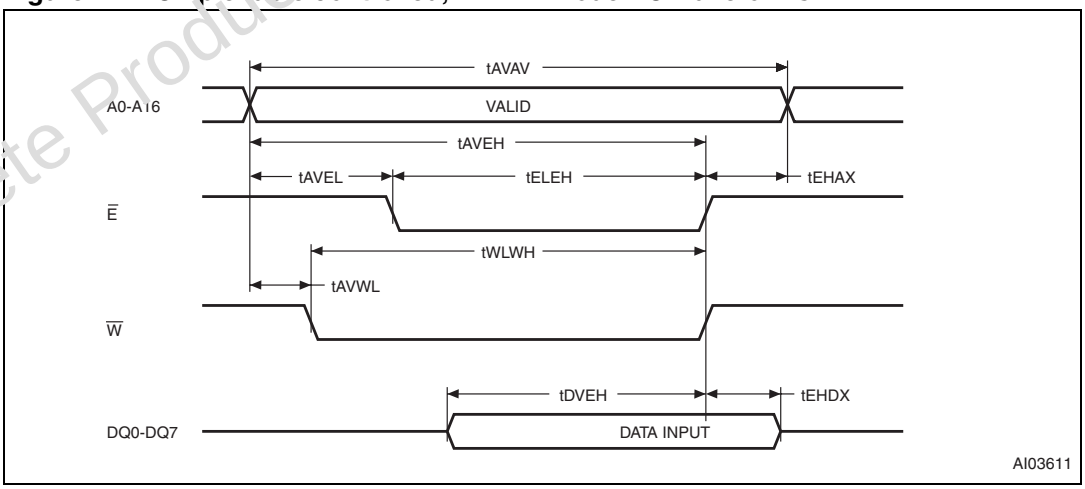


Table 4. WRITE mode AC characteristics

Symbol	Parameter[1]	Min	Max	Unit
t_{AVAV}	WRITE cycle time	85		ns
t_{AVWL}	Address valid to WRITE enable low	0		ns
t_{AVEL}	Address valid to chip enable low	0		ns
t_{WLWH}	WRITE enable pulse width	65		ns
t_{ELEH}	Chip enable low to chip enable high	75		ns
t_{WHAX}	WRITE enable high to address transition	5		ns
t_{EHAX}	Chip enable high to address transition	15		ns
t_{DVWH}	Input valid to WRITE enable high	35		ns
t_{DVEH}	Input valid to chip enable high	35		ns
t_{WHDX}	WRITE enable high to input transition	0		ns
t_{EHDX}	Chip enable high to input transition	15		ns
t_{WLQZ}[2][3]	WRITE enable low to output Hi-Z		30	ns
t_{AVWH}	Address valid to WRITE enable high	75		ns
t_{AVEH}	Address valid to chip enable high	75		ns
t_{WHQX}[2][3]	WRITE enable high to output transition	5		ns

1. Valid for ambient operating temperature: T_A = 0 to 70 °C; V_{CC} = 3.0 to 3.6 V (except where noted).
2. C_L = 5 pF (see *Figure 9*).
3. If $\overline{E}$ goes low simultaneously with $\overline{W}$ going low, the outputs remain in the high impedance state.

2.3 Data retention mode

With valid V_{CC} applied, the M48Z129V operates as a conventional BYTEWIDE™ static RAM. Should the supply voltage decay, the RAM will automatically deselect, write protecting itself when V_{CC} falls between V_{PFD} (max), V_{PFD} (min) window. All outputs become high impedance and all inputs are treated as “Don’t care”.

Note: A power failure during a WRITE cycle may corrupt data at the current addressed location, but does not jeopardize the rest of the RAM’s content. At voltages below V_{PFD}(min), the memory will be in a write protected state, provided the V_{CC} fall time is not less than t_F. The M48Z129V may respond to transient noise spikes on V_{CC} that cross into the deselect window during the time the device is sampling V_{CC}. Therefore, decoupling of the power supply lines is recommended.

When V_{CC} drops below V_{SO}, the control circuit switches power to the internal battery, preserving data. The internal energy source will maintain data in the M48Z129V for an accumulated period of at least 10 years at room temperature. As system power rises above V_{SO}, the battery is disconnected, and the power supply is switched to external V_{CC}. Deselect continues for t_{REC} after V_{CC} reaches V_{PFD}(max).

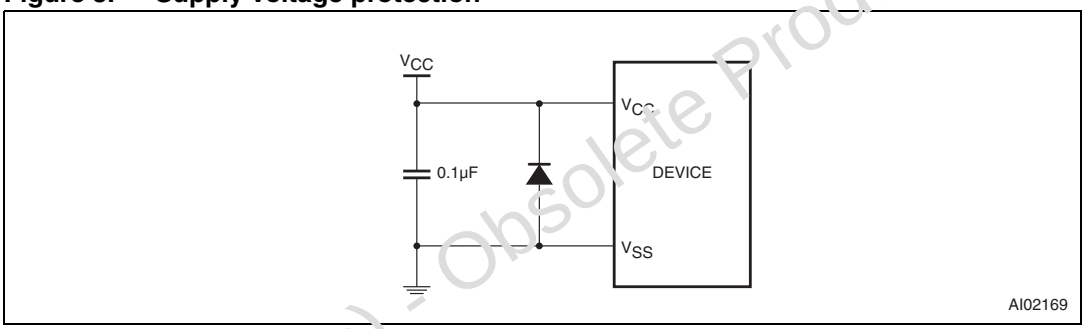
For more information on battery storage life refer to the application note AN1012.

2.4 V_{CC} noise and negative going transients

I_{CC} transients, including those produced by output switching, can produce voltage fluctuations, resulting in spikes on the V_{CC} bus. These transients can be reduced if capacitors are used to store energy which stabilizes the V_{CC} bus. The energy stored in the bypass capacitors will be released as low going spikes are generated or energy will be absorbed when overshoots occur. A ceramic bypass capacitor value of 0.1 µF (as shown in *Figure 8*) is recommended in order to provide the needed filtering.

In addition to transients that are caused by normal SRAM operation, power cycling can generate negative voltage spikes on V_{CC} that drive it to values below V_{SS} by as much as one volt. These negative spikes can cause data corruption in the SRAM while in battery backup mode. To protect from these voltage spikes, it is recommended to connect a Schottky diode from V_{CC} to V_{SS} (cathode connected to V_{CC}, anode to V_{SS}). Schottky diode 1N5817 is recommended for through hole and MBRS120T3 is recommended for surface mount.

Figure 8. Supply voltage protection



3 Maximum ratings

Stressing the device above the rating listed in the absolute maximum ratings table may cause permanent damage to the device. These are stress ratings only and operation of the device at these or any other conditions above those indicated in the operating sections of this specification is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Table 5. Absolute maximum ratings

Symbol	Parameter	Value	Unit
T_A	Ambient operating temperature	0 to 70	°C
T_{STG}	Storage temperature (V_{CC} off, oscillator off)	–40 to 85	°C
T_{SLD}(1)	Lead solder temperature for 10 seconds	260	°C
V_{IO}	Input or output voltages	–0.3 to 7	V
V_{CC}	Supply voltage	–0.3 to 7	V
I_O	Output current	20	mA
P_D	Power dissipation	1	W

1. Soldering temperature of the IC leads is to not exceed 260 °C for 10 seconds. Furthermore, the devices shall not be exposed to IR reflow nor preheat cycles (as performed as part of wave soldering). ST recommends the devices be hand-soldered or placed in sockets to avoid heat damage to the batteries.

Caution: *Negative undershoots below –0.3 V are not allowed on any pin while in the battery backup mode.*

4 DC and AC parameters

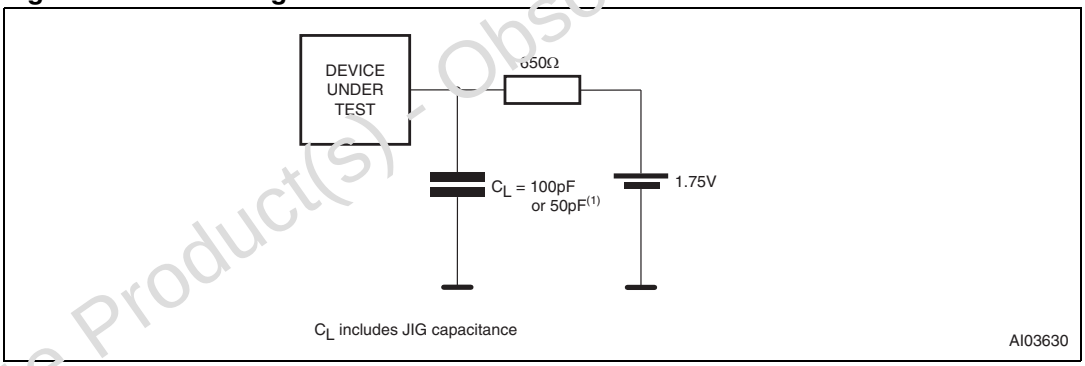
This section summarizes the operating and measurement conditions, as well as the DC and AC characteristics of the device. The parameters in the following DC and AC characteristic tables are derived from tests performed under the measurement conditions listed in the relevant tables. Designers should check that the operating conditions in their projects match the measurement conditions when using the quoted parameters.

Table 6. Operating and AC measurement conditions

Parameter		Unit
Supply voltage (V_{CC})	3.0 to 3.6	V
Ambient operating temperature (T_A)	0 to 70	°C
Load capacitance (C_L)	50	pF
Input rise and fall times	≤ 5	ns
Input pulse voltages	0 to 3	V
Input and output timing ref. voltages	1.5	V

Note: Output Hi-Z is defined as the point where data is no longer driven.

Figure 9. AC testing load circuit



1. 50 pF for M48Z129V (3.3 V).

Table 7. Capacitance

Symbol	Parameter(1)(2)	Min	Max	Unit
C_{IN}	Input capacitance	-	10	pF
C_{IO}(3)	Input / output capacitance	-	10	pF

1. Effective capacitance measured with power supply at 5 V; sampled only, not 100% tested.
2. At 25 °C, f = 1 MHz.
3. Outputs deselected.

Table 8. DC characteristics

Sym	Parameter	Test condition(1)	Min	Max	Unit
I_{LI}	Input leakage current	$0 V \le V_{IN} \le V_{CC}$		±1	µA
I_{LO}(2)	Output leakage current	$0 V \le V_{OUT} \le V_{CC}$		±1	µA
I_{CC}	Supply current	Outputs open		50	mA
I_{CC1}	Supply current (standby) TTL	$\overline{E} = V_{IH}$		4	mA
I_{CC2}	Supply current (standby) CMOS	$\overline{E} = V_{CC} - 0.2 V$		3	mA
V_{IL}	Input low voltage		–0.3	0.6	V
V_{IH}	Input high voltage		2.2	V_{CC} + 0.3	V
V_{OL}	Output low voltage	I_{OL} = 2.1 mA		0.4	V
V_{OH}	Output high voltage	I_{OH} = –1 mA	2.2		V

1. Valid for ambient operating temperature: T_A = 0 to 70 °C; V_{CC} = 3.0 to 3.6 V (except where noted).
2. Outputs deselected.

Figure 10. Power down/up mode AC waveforms

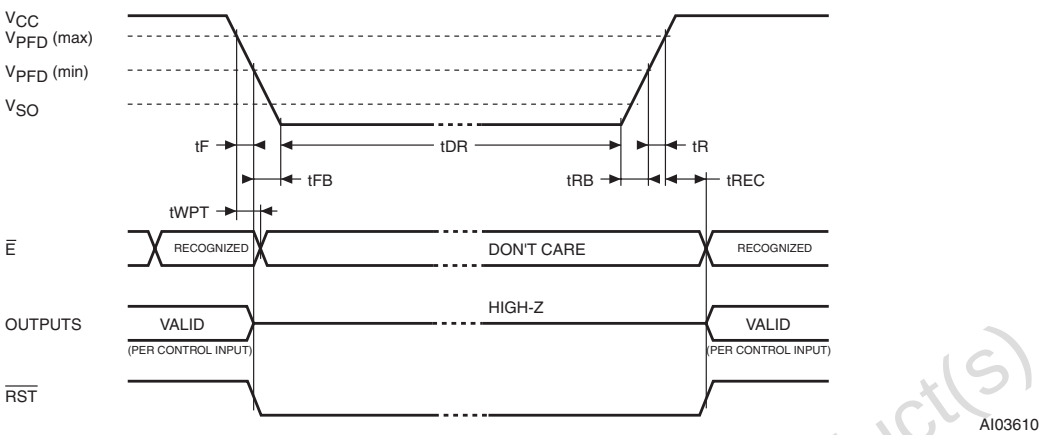


Table 9. Power down/up AC characteristics

Symbol	Parameter[1]	Min	Max	Unit
t_F[2]	V_{PFD} (max) to V_{PFD} (min) V_{CC} fall time	300		µs
t_{FB}[3]	V_{PFD} (min) to V_{SS} V_{CC} fall time	150		µs
t_R	V_{PFD} (min) to V_{PFD} (max) V_{CC} rise time	10		µs
t_{RB}	V_{SS} to V_{PFD} (min) V_{CC} rise time	1		µs
t_{WPT}	Write protect time	40	250	µs
t_{REC}	V_{PFD} (max) to $\overline{RST}$ high	40	200	ms

1. Valid for ambient operating temperature: T_A = 0 to 70 °C; V_{CC} = 3.0 to 3.6 V (except where noted).
2. V_{PFD} (max) to V_{PFD} (min) fall time of less than t_F may result in deselection/write protection not occurring until 200 µs after V_{CC} passes V_{PFD} (min).
3. V_{PFD} (min) to V_{SS} fall time of less than t_{FB} may cause corruption of RAM data.

Table 10. Power down/up trip points DC characteristics

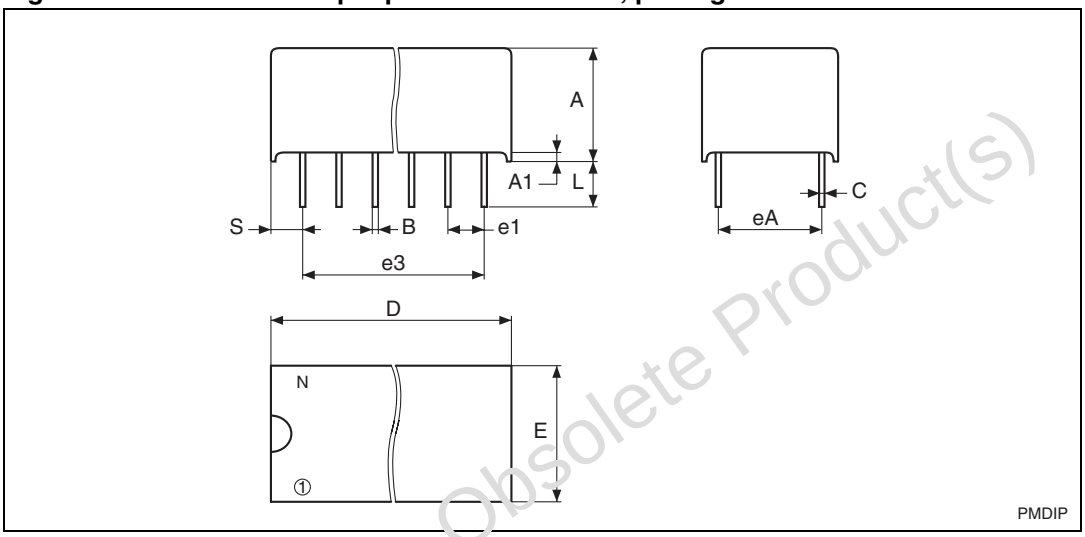
Symbol	Parameter[1][2]	Min	Typ	Max	Unit
V_{PFD}	Power-fail deselect voltage	2.7	2.9	3.0	V
V_{SO}	Battery backup switchover voltage		2.45		V
t_{DR}[3]	Expected data retention time	10			Years

1. All voltages referenced to V_{SS}.
2. Valid for ambient operating temperature: T_A = 0 to 70 °C; V_{CC} = 3.0 to 3.6 V (except where noted).
3. At 25 °C, V_{CC} = 0 V.

5 Package mechanical data

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: *www.st.com*. ECOPACK® is an ST trademark.

Figure 11. PMDIP32 – 32-pin plastic module DIP, package outline



Note: Drawing is not to scale.

Table 11. PMDIP32 - 32-pin plastic DIP, package mechanical data

Symb	mm			inches		
	Typ	Min	Max	Typ	Min	Max
A		9.27	9.52		0.365	0.375
A1		0.38	–		0.015	–
B		0.43	0.59		0.017	0.023
C		0.20	0.33		0.008	0.013
D		42.42	43.18		1.670	1.700
E		18.03	18.80		0.710	0.740
e1		2.29	2.79		0.090	0.110
e3	38.1			1.5		
eA		14.99	16.00		0.590	0.630
L		3.05	3.81		0.120	0.150
S		1.91	2.79		0.075	0.110
N	32			32		

6 Part numbering

Table 12. Ordering information scheme

Example: M48Z 129Y –70 PM 1

Device Type

M48Z

Supply voltage and write protect voltage

129V(1) = V_{CC} = 3.0 to 3.6 V; 2.7 V ≤ V_{PFD} ≤ 3.0 V

Speed

–85 = 85 ns

Package

PM = PMDIP32

Temperature range

1 = 0 to 70 °C

Shipping method

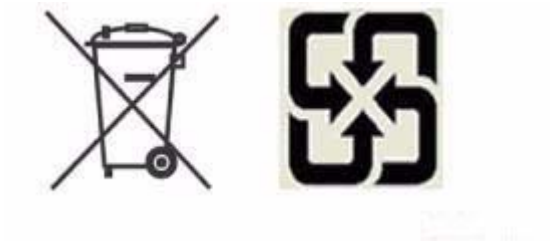
blank = ECOPACK® package, tubes

1. Device is not recommended for new design. Contact local ST sales office for availability.

For other options, or for more information on any aspect of this device, please contact the ST sales office nearest you.

7 Environmental information

Figure 12. Recycling symbols



This product contains a non-rechargeable lithium (lithium carbon monofluoride chemistry) button cell battery fully encapsulated in the final product.

Recycle or dispose of batteries in accordance with the battery manufacturer's instructions and local/national disposal and recycling regulations.

8 Revision history

Table 13. Document revision history

Date	Revision	Changes
Dec-1999	1	First issue
30-Mar-2000	2	From preliminary data to datasheet
20-Jun-2000	2.1	t_{GLQX} changed for M48Z129Y (*Table 3*)
14-Sep-2001	3	Reformatted; temperature information added to tables (*Table 7*, *8*, *3*, *4*, *9*, *10*)
29-May-2002	3.1	Add countries to disclaimer
02-Apr-2003	4	v2.2 template applied; test condition updated (*Table 10*)
18-Feb-2005	5	Reformatted; IR reflow update (*Table 5*)
22-Apr-2010	6	Updated *Table 11*, *12*, footnote *1* of *Table 5*; added Ecopack® text to *Section 5*; reformatted document.
23-Jun-2010	7	Updated *Features*, *Table 11*; added *Section 7. Environmental information*; minor textual changes.
26-Sep-2011	8	Devices are not recommended for new design (updated cover page, *Table 12*); updated footnote of *Table 5: Absolute maximum ratings*; updated *Section 7: Environmental information*; removed M48Z129Y.

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